

OL-NX3P2902B

wafer level chip-scale package; 4 bumps; 0.77 x 0.77 x 0.51 mm (Backside coating included)

8 February 2016

Package information

1. Package summary

Terminal position code	B (bottom)
Package type descriptive code	WLCSP
Package type industry code	WLCSP
Package style descriptive code	UC (uncased chip)
Package style suffix code	NA (not applicable)
Package body material type	X (other)
IEC package outline code	---
JEDEC package outline code	---
JEITA package outline code	---
Mounting method type	S (surface mount)
Issue date	2-4-2013

Table 1. Package summary

Symbol	Parameter	Min	Typ	Nom	Max	Unit
D	package length	0.74	-	0.77	0.8	mm
E	package width	0.74	-	0.77	0.8	mm
A	seated height	0.48	-	0.51	0.54	mm
A ₂	package height	0.29	-	0.31	0.33	mm
e	nominal pitch	-	-	0.4	-	mm
n ₂	actual quantity of termination	-	-	4	-	



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2. Package outline

WLCSP4: wafer level chip-scale package; 4 bumps; 0.77 x 0.77 x 0.51 mm (Backside coating included) NX3P2902B

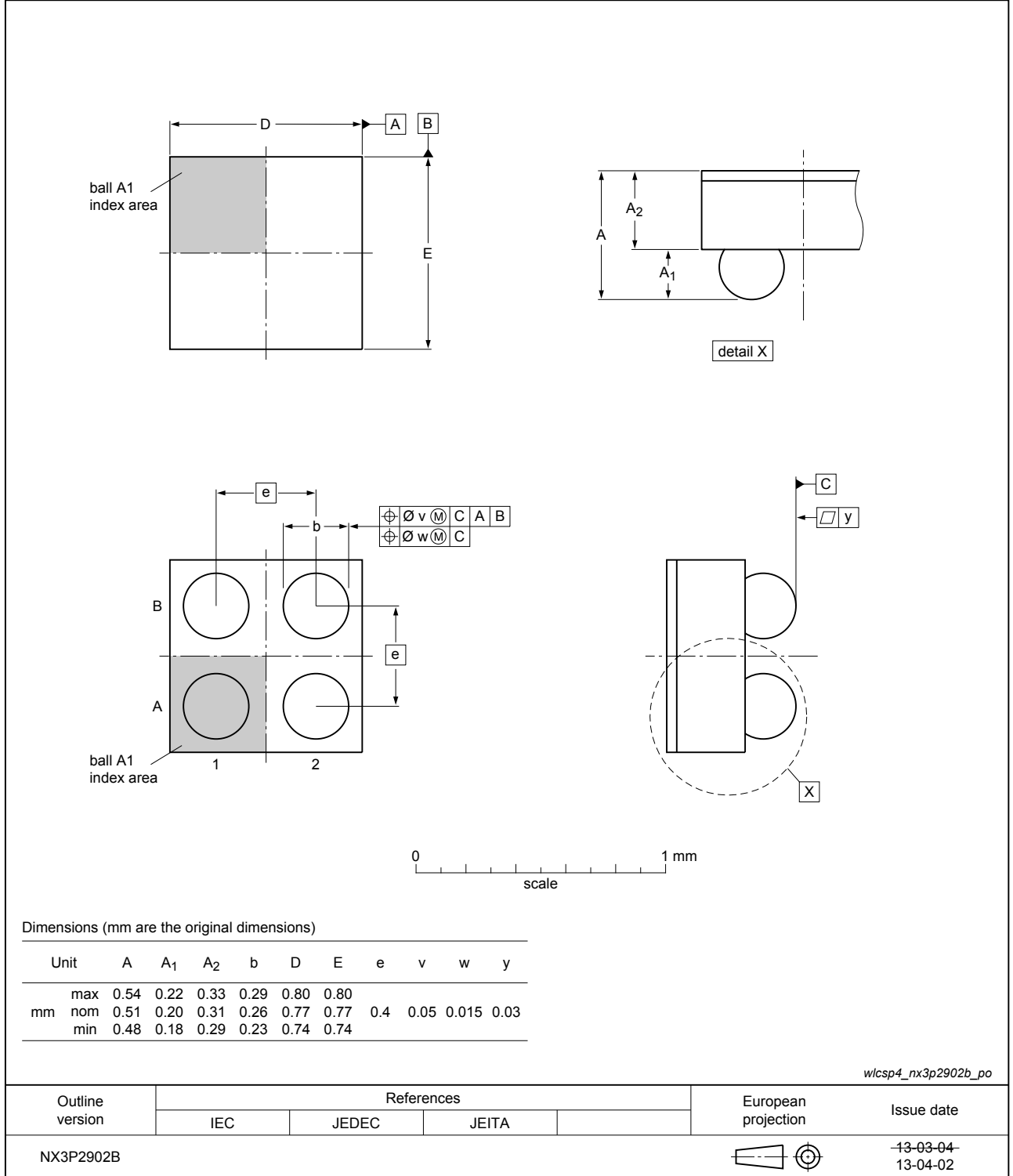


Fig. 1. Package outline WLCSP (OL-NX3P2902B)

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0.77 x 0.51 mm (Backside coating included)

3. Legal information

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